

preparing a substrate;

forming an anti-stiction layer that is removed by dry etching for preventing stiction on the substrate;

forming a sacrificial layer that is removed by wet etching on the substrate;

removing parts of the anti-stiction layer and the sacrificial layer so that a part of the substrate is exposed and forming a resulting structure including a post; and

forming at least one structure layer for forming at least one microstructure over the resulting structure.

9. (Amended) A method for fabricating microstructures, the method comprising:

preparing a substrate;

forming an anti-stiction layer on the substrate;

forming a sacrificial layer on the anti-stiction layer;

forming at least one structure layer for creating at least one microstructure on the sacrificial layer; and

removing the sacrificial layer by a first etching and removing the anti-stiction layer by a second etching in order to release the at least one microstructure while preventing stiction.

15. (Amended) A method of fabricating microstructures, the method comprising:

preparing a substrate;

forming a sacrificial layer on the substrate;

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forming an anti-stiction layer on the sacrificial layer; and

forming at least one structure layer for forming at least one microstructure on the anti-stiction layer and removing the sacrificial layer by wet etching while removing the anti-stiction layer by dry etching in order to release the at least one microstructure while preventing stiction.